

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3851360

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MATT YEY	03/02/2009
SHUN WU LIN	03/02/2009
RYAN CHIA-JEN CHEN	03/05/2009
YI-HSING CHEN	03/03/2009
CHIEN-HAO CHEN	03/03/2009
DONALD Y. CHAO	03/05/2009
KUO-BIN HUANG	03/03/2009
CHI-CHUN CHEN	03/17/2009
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN ROAD 6,
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14673024
CORRESPONDENCE DATA	
Fax Number:	(214)651-5940
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	24061.2367US04
NAME OF SUBMITTER:	LADONNA JOHNSON

PATENT

SIGNATURE:	/LaDonna Johnson/
DATE SIGNED:	04/28/2016
Total Attachments: 8 source=Assignment1#page1.tif source=Assignment1#page2.tif source=Assignment1#page3.tif source=Assignment1#page4.tif source=Assignment2#page1.tif source=Assignment2#page2.tif source=Assignment2#page3.tif source=Assignment2#page4.tif	

Docket No.: 2008-0465 (0457, 0458, 0459) / 24061.1096
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Matt Yeh of 6F, 6, Ching-San Street 28
Hsinchun, Taiwan, R.O.C.
- (2) Shun Wu Lin of No. 28, Jlande Street, East District
Taichung City 401, Taiwan, R.O.C.
- (3) Chi-Chun Chen of 8F, No. 56, Chang Sheng Road, Gushan Chiu
Kaohsiung, Taiwan, R.O.C.
- (4) Ryan Chia-Jen Chen of No. 182, Minchuan Road
Chiayi, Taiwan, R.O.C.
- (5) Yi-Hsing Chen of , Taiwan, R.O.C.
- (6) Chien-Hao Chen of No. 37, Sec. 1, Chuangbin Road
Chuangwei Township, Ilan County, Taiwan, R.O.C.
- (7) Donald Y. Chao of 12F-3, No. 272, Guangfu Road, Sec. 1
Hsinchu City 300, Taiwan, R.O.C.
- (8) Kuo-Bin Huang of , Taiwan, R.O.C.

have invented certain improvements in

METHOD OF PATTERNING A METAL GATE OF SEMICONDUCTOR DEVICE

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on and assigned application no. and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and sot over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and

Docket No.: 2008-0465 (0457, 0458, 0459) / 24061.1096

Customer No.: 42717

assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Matt Yeh

Residence Address: 6F, 6, Ching-San Street 28
Hsinchun, Taiwan, R.O.C.

Dated: 3/2 '09

Matt Yeh
Inventor Signature

Inventor Name: Shun Wu Lin

Residence Address: No. 28, Jiande Street, East District
Taichung City 401, Taiwan, R.O.C.

Dated: 3/2 '09

Shun Wu Lin
Inventor Signature

Docket No.: 2008-0465 (0457, 0458, 0459) / 24061.1096
Customer No.: 42717

Inventor Name: Chi-Chun Chen

Residence Address: 8F, No. 56, Chang Sheng Road, Gushan Chiu
Kaohsiung, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Ryan Chia-Jen Chen

Residence Address: No. 182, Minchuan Road
Chiayi, Taiwan, R.O.C.

Dated: 3/5/2009

Inventor Signature

Inventor Name: Yi-Hsing Chen

Residence Address: _____, Taiwan, R.O.C.

Dated: 3/7 '2009

Inventor Signature

Inventor Name: Chien-Hao Chen

Residence Address: No. 37, Sec. 6, Chuangbin Road
Chuangwei Township, Ilan County, Taiwan, R.O.C.

Dated: 3/3 '2009

Inventor Signature

Docket No.: 2008-0465 (0457, 0458, 0459) / 24061.1096
Customer No.: 42717

Inventor Name: Donald Y. Chao

Residence Address: 12F-3, No. 272, Guangfu Road, Sec. 1
Hsinchu City 300, Taiwan, R.O.C.

Dated: 3/5 '09 Donald Y. Chao
Inventor Signature

Inventor Name: Kuo-Bin Huang

Residence Address: , Taiwan, R.O.C.

Dated: 3/3 '09 Kuo-Bin Huang
Inventor Signature

ASSIGNMENT

WHEREAS, we,

- (1) Matt Yeh of 6F, 6, Ching-San Street 28
Hsinchun, Taiwan, R.O.C.
- (2) Shun Wu Lin of No. 28, Jiande Street, East District
Taichung City 401, Taiwan, R.O.C.
- (3) Chi-Chun Chen of 8F, No. 56, Chang Sheng Road, Gushan Chiu
Kaohsiung, Taiwan, R.O.C.
- (4) Ryan Chia-Jen Chen of No. 182, Minchuan Road
Chiayi, Taiwan, R.O.C.
- (5) Yi-Hsing Chen of _____, Taiwan, R.O.C.
- (6) Chien-Hao Chen of No. 37, Sec. 1, Chuangbin Road
Chuangwei Township, Ilan County, Taiwan, R.O.C.
- (7) Donald Y. Chao of 12F-3, No. 272, Guangfu Road, Sec. 1
Hsinchu City 300, Taiwan, R.O.C.
- (8) Kuo-Bin Huang of _____, Taiwan, R.O.C.

have invented certain improvements in

**METHOD OF PATTERNING A METAL GATE
OF SEMICONDUCTOR DEVICE**

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on _____ and assigned application no. _____ and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and

assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Matt Yeh

Residence Address: 6F, 6, Ching-San Street 28
Hsinchun, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Shun Wu Lin

Residence Address: No. 28, Jiande Street, East District
Taichung City 401, Taiwan, R.O.C.

Dated: _____

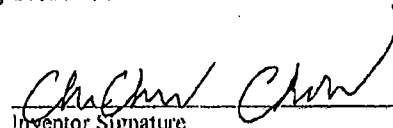
Inventor Signature

Docket No.: 2008-0465 (0457, 0458, 0459) / 24061.1096
Customer No.: 42717

Inventor Name: Chi-Chun Chen

Residence Address: 8F, No. 56, Chang Sheng Road, Gushan Chiu
Kaohsiung, Taiwan, R.O.C.

Dated: 03-17-09


Inventor Signature

Inventor Name: Ryan Chia-Jen Chen

Residence Address: No. 182, Minchuan Road
Chiayi, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Yi-Hsing Chen

Residence Address: _____
_____, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Chien-Hao Chen

Residence Address: No. 37, Sec. 6, Chuangbin Road
Chuangwei Township, Ilan County, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Donald Y. Chao

Residence Address: 12F-3, No. 272, Guangfu Road, Sec. 1
Hsinchu City 300, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Kuo-Bin Huang

Residence Address:

, Taiwan, R.O.C.

Dated: _____

Inventor Signature